## TRD chamber type 5 production

TRD retreat, Dorfweil/Taunus, 07 November 2023

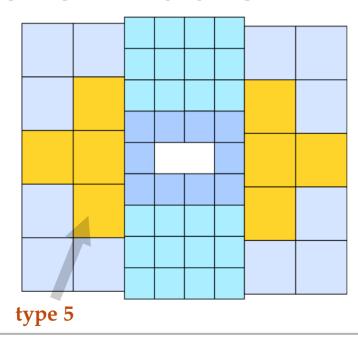
Philipp Kähler

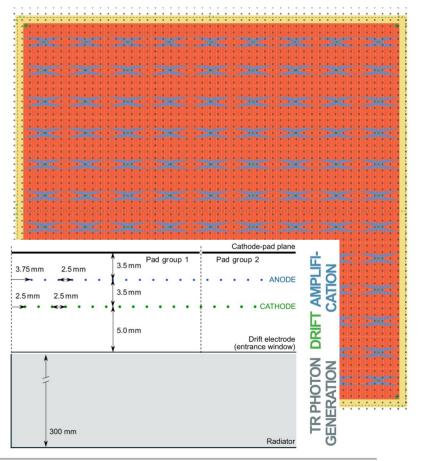
## overview

- production status
- production step details
- QA
- issues

# type 5, design count

- **32+3 TRD chambers**, 990 mm x 990 mm, 144 x 24 pads
- highest pad granularity of outer TRD, 6.7 mm x 40 mm
- 2 preseries chambers produced, shall serve as base for PRR measurements
- component production ongoing: backpannel carriers, entrance windows





# production status, type 5

split production
 Ms entrance window, backpanel referencing, padplane glueing
 Fra wire winding & mounting (both layers), chamber closing

# entrance windows 22 35 backpanel carriers 10 backpanels with padplane 2 chambers wired & closed 2 35

- timeline (target):
  - scale up to 1 chamber per week, starting early 2024
  - required: preseries confirmation & PRR

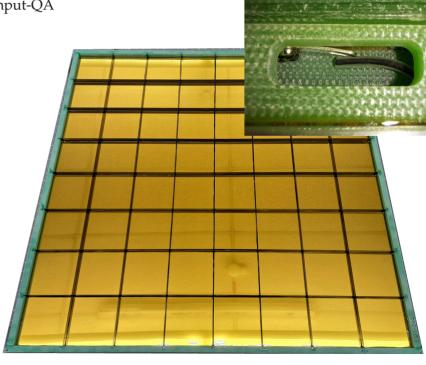
#### transport

- batches of 5 to 10 (windows + backpanels)
   Ms → Fra
- further component boxes are being prepared
- keep boxes @IKF for storage?
- return 5 to 10 chambers to Ms for QA & storage
- transport containment t.b.d.



## component: entrance window

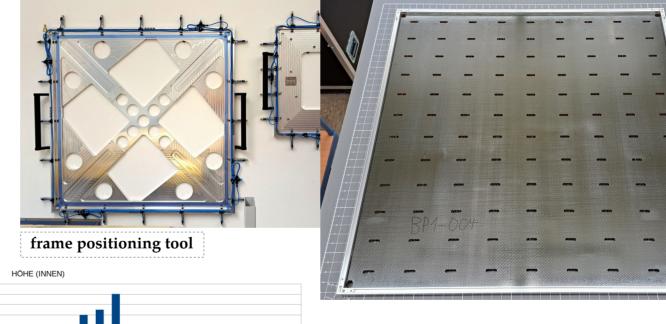
- entrance window foil
  - new batch of Al-coated polyimide (*Kapton*, 25 μm) foil received, sufficient coverage for full TRD production
  - Al-coating ~ 50 ... 100 nm strongly depends on foil conditions → accurate input-QA
  - Al layer as moisture barrier, defined by thickness and homogeneity
  - optical inspection: screening agrees with earlier production, Al weighting: ~ 70 ... 80 nm, humidity transmission: talk Felix, ~ compatible range
    - → input parameter for gas system demands
- pre-stretching of foil on thermal desk, acrylic glas
  - flatness optimised by symmetrical design
  - PID controller for temperature, constant  $\Delta T$
  - monitor stretcher expansion, replace if necessary
- cut of foil 2 mm behind outer edge, HV safety
- re-order window ledges after partial usage for test chambers

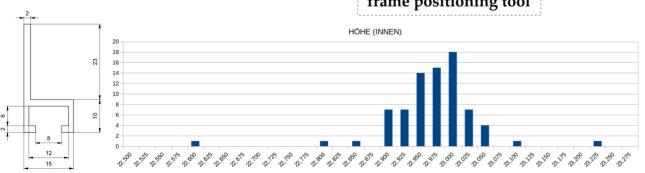


## component: backpanel carrier

- revised Al frame, extrusion according to own design, profile notch integrated (e.g. gas inlet fixation)
- height matching honeycomb 

  Al profile
- signal cable openings by water jet cut, inhouse

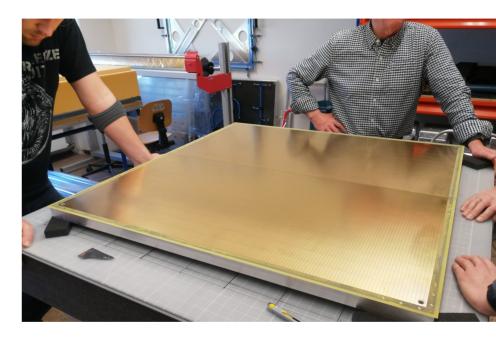




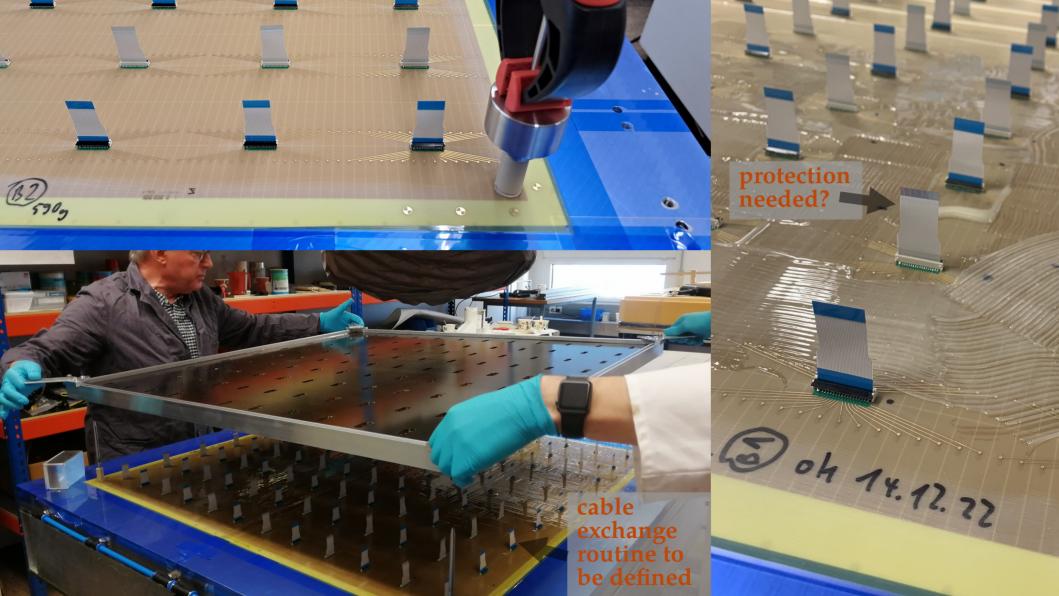
# component: backpanel

#### padplane

- 4-layered PCB, intrinsic gas tightness by displacedvias
- 2 segments per chamber alignment using gas mounts in PCB
- ENIG surface, 0.05 to 0.10 μm Au
- external/automatised soldering of signal connectors
- revised glueing process:no carrier foil, directly on vacuum table
  - glueing test to honeycomb:
     < 20 μm flatness (segment edge),</li>
     < 10 μm within segments</li>
  - epoxy Araldite 2011: ~ 400 g/m², monitored
- batches: 8 half v1 + 10 half v2 + 52 half v2
  - v1 design problematic during ENIG handling, contact curing @Ms
  - v2 with change of Cu balance, improve handling for manufacturer



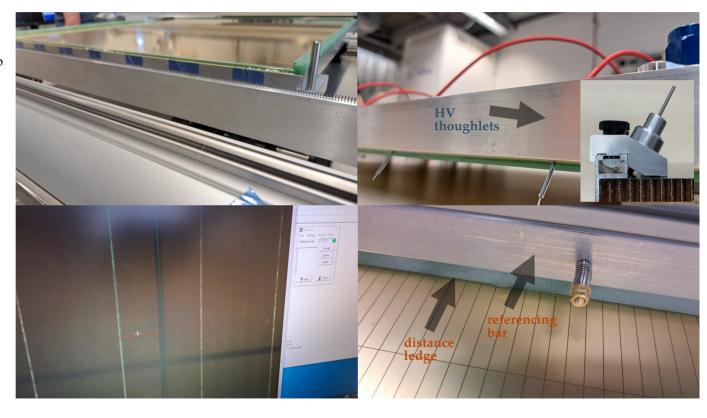




## component: wire system

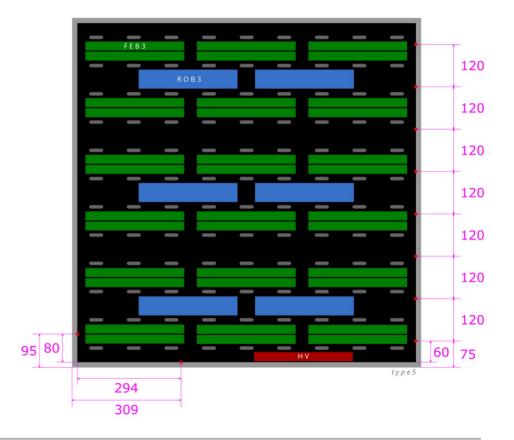
#### layer alignment

- pitch regularisation and positioning with precision comb
- outermost cathode: 2.5 mm from ledge
- outermost anode: 1.25/3.75 mm
- define tolerance
- wire ledge system
  - new referencing bar developed
  - revised glue dosing (gas tightness), define
- wire contacting
  - new drilling tool for HV throughlets
  - 8 anode segments (decoupling)
- atmosphere: 23 ... 30 °C, < 30% rH for HV-safe epoxy



# type 5, outlook, backside layout

- HV contacting arranged according to drawing (this slide)
- FEB and ROB arrangement to be confirmed, depending on layout
  - FEB layout @ Fra,
     ROB project started @ Ms

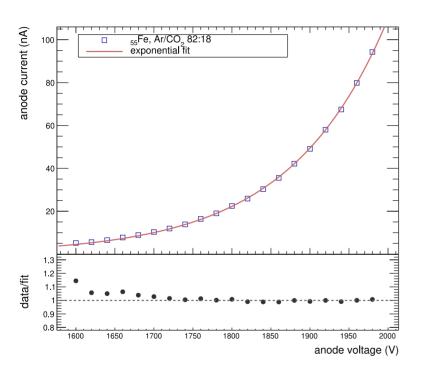


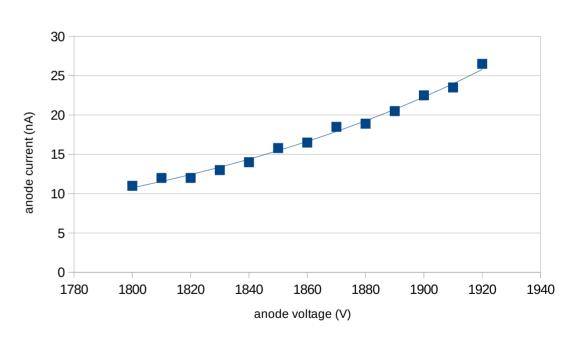
### QA

- regular measurements:
  - gas tightness, direct measurement (talk Felix)
     → every chamber
     available,
     first chamber: (0.83 + 0.33) ml/h
  - humidity collection (talk Felix)
     → first 10 chambers, then define available, clarify dependencies
  - gas gain scan
     → every chamber
     auto-test stand available, awaiting new <sup>55</sup>Fe source
  - readout test
     → every chamber
     after FEE equipment, single-FEB test before
- install comprehensive test stand in Ms



## "chamber 0", begin of gain scan





prototype chamber, type 8/2016, scan 2020 ~1 source halftime in between

first chamber, type 5

## "chamber 0", HV situation

- chamber HV stable over hours @ 1900 | -500 V with 7 of 8 anode segments connected
- dark currents < 150 nA</li>
- with 8 of 8 segment connected, trips reproducible @ 1100 ... 1200 V
  - instant current rise
  - few times such trip triggered LV-current behaviour, which then cures
- gravitational sag of outermost wire should not be relevant, ~ 40  $\mu m$
- strategy:
  - exclude electrostatic sag by comparison to segment on other side
  - reconsider 1.25/3.75 mm anode-to-ledge question
  - optical inspection of wire contacting region
  - consider HV test series with epoxy batch
  - identify current (charge) path



## summary

#### **PRODUCTION**

- chamber production type 5,
   32 +3 chambers
  - 2 chambers produced
  - production of components ongoing in advance,
     i.e. entrance windows and backpanel carriers
- transport modus Ms 
   ← Fra suggested
- presentation of production step details
- touched given and open value defintions, e.g. glue dosing amounts

#### **OA AND ISSUES**

- QA being commissioned, further deploy test stand in next weeks
  - awaiting new <sup>55</sup>Fe source for spatially resolved (pad) gain map
  - gas tightness and humidity measurements available
- gas tightness measured within limits,
- first chamber shows good HV stability except for one anode segment
  - test strategy being followed

## **END**

(backup following)

# direct wire pitch measure?

- wire tension device can extract also wire positions
  - main uncertainties from linear drive, but not from actual wire positions
  - improvement of linear drive?
     might not be necessary, documentary only.

